

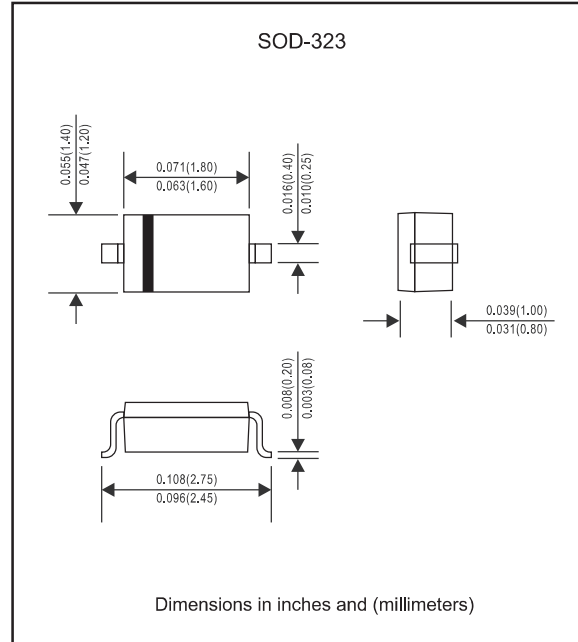
Features

- Low Forward Voltage Drop
- Surface Device Type Mounting
- Lead-free parts for green partner, exceeds environmental standards of MIL-STD-19500 /228
- Compliant to Halogen-free

Mechanical data

- Epoxy:UL94-VO rated flame retardant
- Case : Molded plastic, SOD-323
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

Package outline



Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

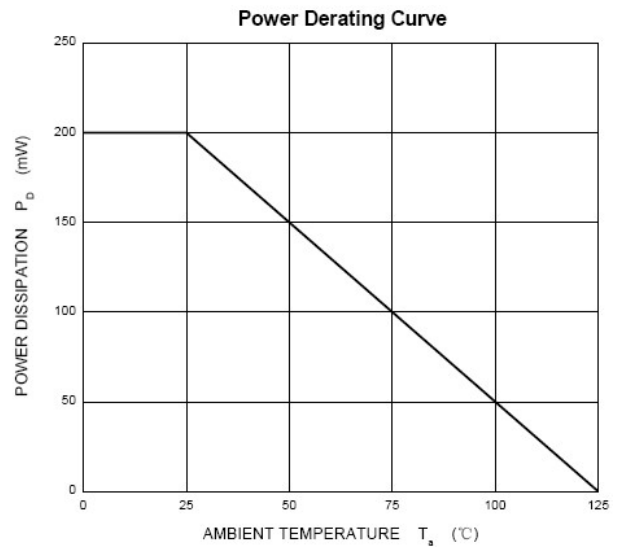
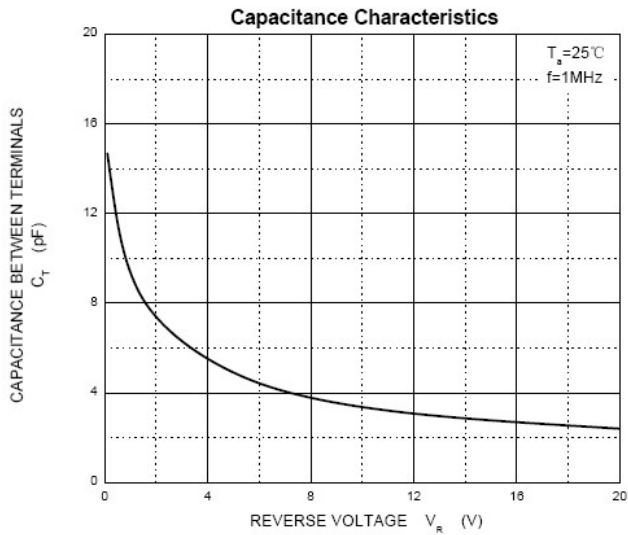
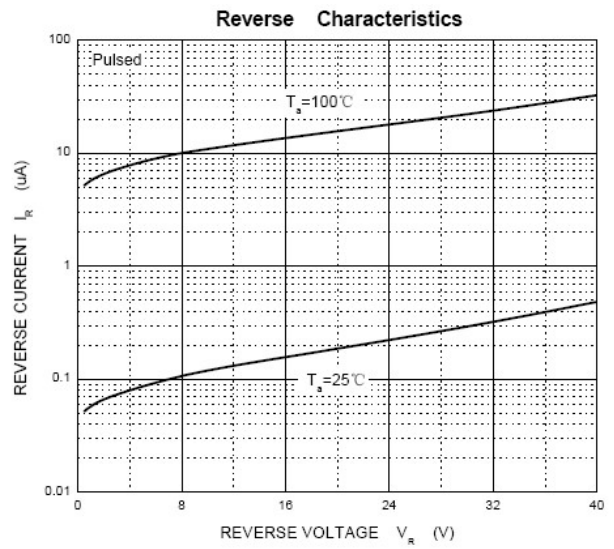
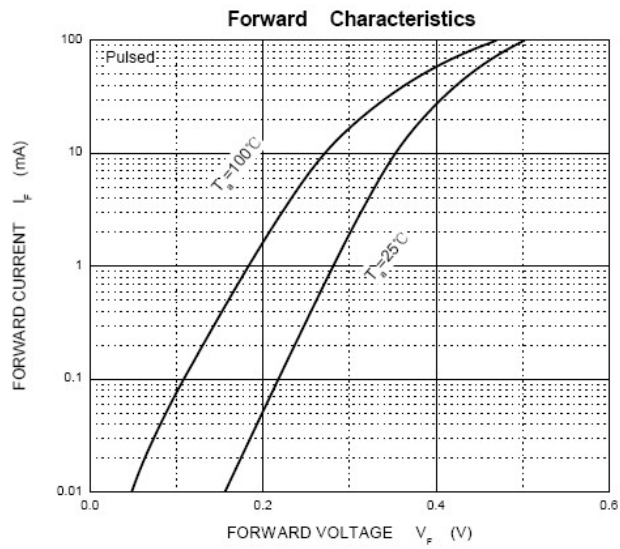
PARAMETER	CONDITIONS	Symbol	Value	UNIT
Power Dissipation		P_D	200	mW
Repetitive Peak Reverse Voltage		V_{RRM}	40	V
Reverse Voltage		V_R	30	V
Forward Current		I_F	30	mA
Non-Repetitive Peak Forward Current	60Hz for 1cycle	I_{FSM}	200	mA
Operating Junction Temperature		T_J	+125	$^{\circ}\text{C}$
Storage Temperature Range		T_{STG}	-55~+125	$^{\circ}\text{C}$

These ratings are limiting values above which the serviceability of the diode may be impaired.

Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Breakdown Voltage	$I_R = 10\mu\text{A}$	V_{BR}	30			V
Forward voltage	$I_F = 1.0\text{ mA}$	V_F			0.37	V
Reverse current	$V_R = 30\text{ V}$	I_R			0.5	μA
Diode capacitance	$V_R = 10\text{ V}, f = 1\text{MHz}$	C_T		6.0		pF

Rating and characteristic curves (RB751V-40)



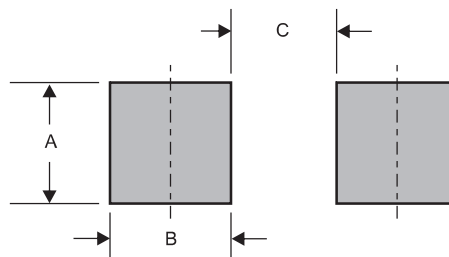
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
RB751V-40	5

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-323	0.032 (0.82)	0.022 (0.56)	0.069 (1.75)